

• General Description

The AGM12T12C combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

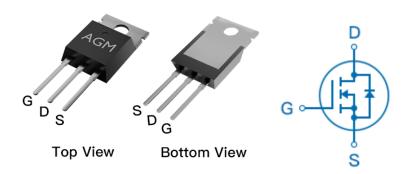
Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
120V	10mΩ	60A

TO-220 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM12T12C	AGM12T12C	TO-220			1000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	120	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	60	А
	Drain Current-Continuous(Tc=100℃)	36	Α
IDM (pluse)	Drain Current-Pulsed (Note 2)	240	А
PD	Maximum Power Dissipation(Tc=25℃)	33	W
	Maximum Power Dissipation(Tc=100℃)	13	W
EAS	Avalanche energy (Note 3)	256	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹		62.5	°C/W
RøJC	Thermal Resistance Junction-Case ¹		3.78	°C/W



Table 3. Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off Sta	tes					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	120			V
IDSS	Zero Gate Voltage Drain Current	VDS=120V,VGS=0V			1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2	1.7	2.2	V
gFS	Forward Transconductance	VDS=5V,ID=15A		27		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A		10	14	mΩ
(0)		VGS=4.5V, ID=15A		11	16	mΩ
Dynamic C	Characteristics					
Ciss	Input Capacitance	VDS=40V,VGS=0V,		2208		pF
Coss	Output Capacitance	F=1MHZ		539		pF
Crss	Reverse Transfer Capacitance			25		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		0.56		Ω
Switching	Times					
td(on)	Turn-on Delay Time			18		nS
tr	Turn-on Rise Time	VGS=10V,VDS=50V,		5		nS
td(off)	Turn-Off Delay Time	ID=25A,RGEN=2Ω		43		nS
tf	Turn-Off Fall Time			6.3		nS
Qg	Total Gate Charge			40		nC
Qgs	Gate-Source Charge	VGS=10V, VDS=50V, ID=25A		7		nC
Qgd	Gate-Drain Charge			8		nC
Source-Dra	ain Diode Characteristics					
ISD	Source-Drain Current(Body Diode)				60	Α
VSD	Forward on Voltage	VGS=0V,IS=20A			1.2	V
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/μs ,			79.5	ns
Qrr	Reverse Recovery Charge	TJ=25℃			210	nc

Notes 1. The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25 $^{\circ}\text{C}$, VDD=50V,Vgs=10V , ID=32A,L=0.5mH,RG=25ohm



■ Electrical Characteristics Diagrams

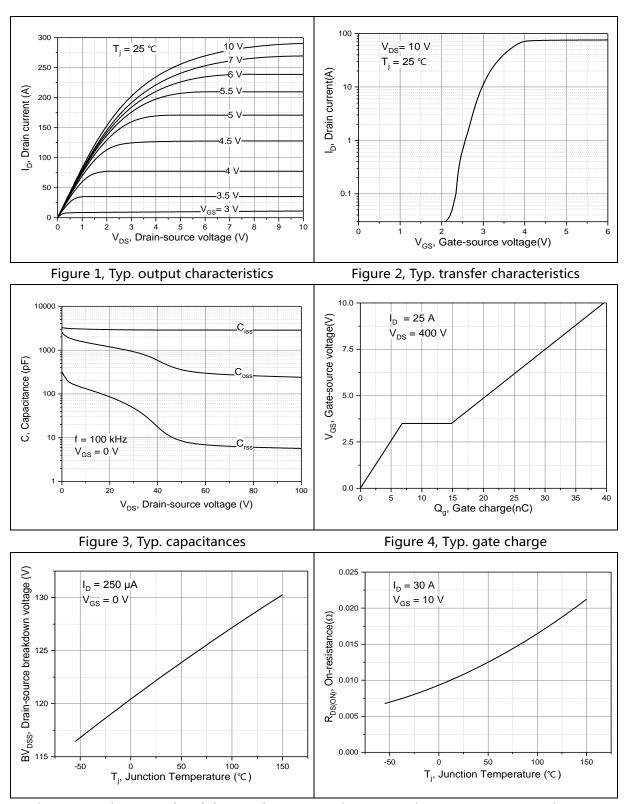


Figure 5, Drain-source breakdown voltage

Figure 6, Drain-source on-state resistance



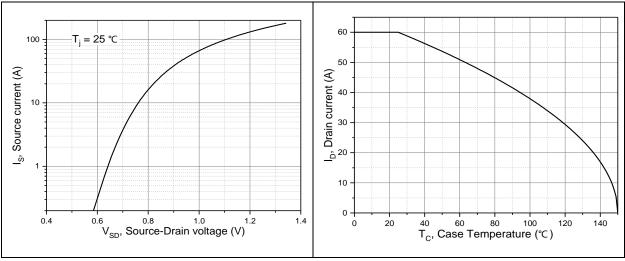


Figure 7, Forward characteristic of body diode

Figure 8, Drain current

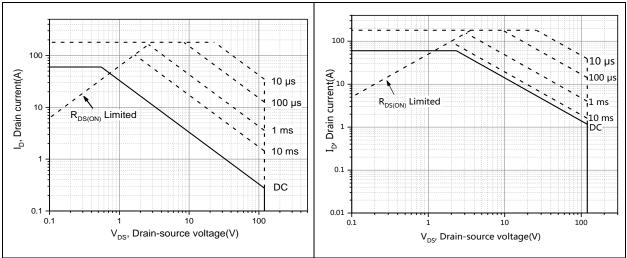


Figure 9, Safe operation area for TO220F T_C =25 °C

Figure 10, Safe operation area for TO220 T_C =25 $^{\circ}C$



■ Test circuits and waveforms

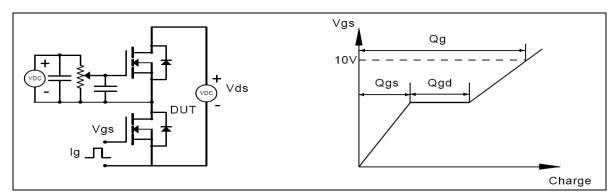


Figure 1, Gate charge test circuit & waveform

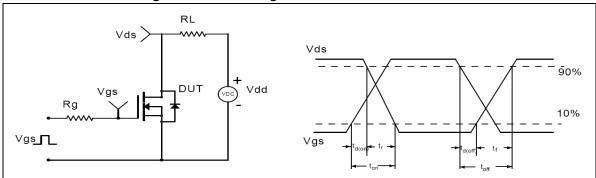


Figure 2, Switching time test circuit & waveforms

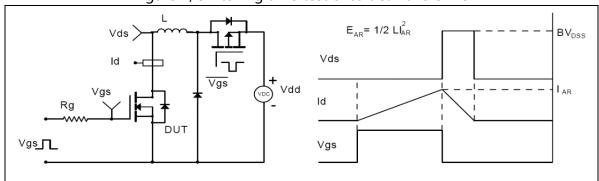


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

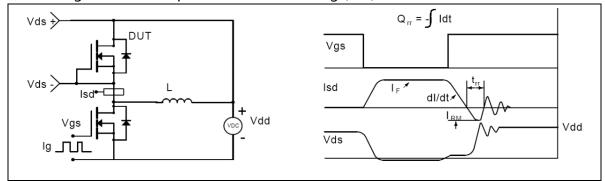
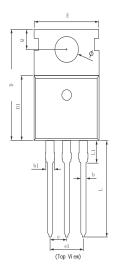


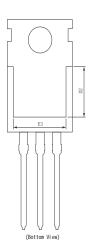
Figure 4, Diode reverse recovery test circuit & waveforms



•Dimensions (TO-220)

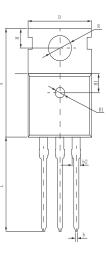


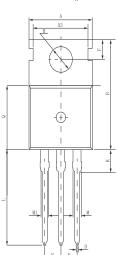




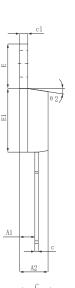
SYMBOL	MILLIMETER		
SIMDUL	MIN	Typ.	MAX
A	4.370	4.570	4.700
A1	1. 250	1.300	1.400
A2	2. 150	2.350	2.550
b	0.700	0.800	0.950
b1	1. 170	1.270	1.470
С	0.450	0.500	0.600
D	15. 100	15.600	16. 100
D1	8.800	9.100	9.400
D2	5. 500	6.300 REF	
Е	9. 700	10.000	10.300
E3	7.000	7.600 REF	
е	2.540 BSC		
e1	5.080 BSC		
L	13. 200	13. 500	13.800
L1		3.100	3.400
Н	6. 250	6.500	1.352
Φ	3. 400	3.600	3.800
Q	2.600	2.800	3.000
θ 1	7° TYP		
θ2	7° TYP		
θ 3	3° TYP		

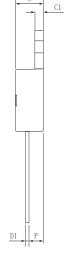


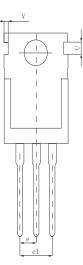


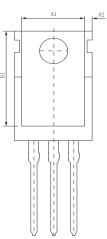












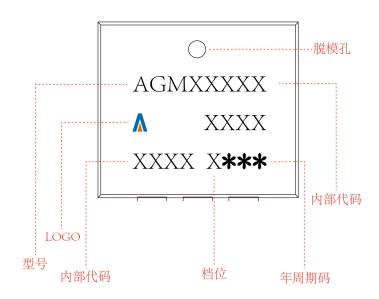
SYMBOL.		MILLIMETER	
SIMDUL	MIN	Тур.	MAX
A	15.400	15.600	15.800
A1	2.350	2. 400	2.500
A2	4.400	4. 500	4.700
b	0.700	0.800	0.900
b2	1.180	1.310	1.440
С	0.480	0.500	0.560
c1	1.290	1.300	1.320
D	9.800	10.000	10. 200
Е	6.400	6. 500	6.600
E1	9.000	9.100	9.200
е	2. 420	2. 540	2.660
e1	4.840	5.080	5. 320
Н	2.730	2.800	2.870
H1	2.400	2. 500	2.600
L	13.020	13.370	13.720
R	3.500	3. 600	3. 730
R1	1.400	1.500	1.600
U	1.650	1.750	1.850
V	0.580	0.680	0.780
θ 1	2°	2.5°	3°
θ2	6.5°	7°	7.5°

Symbol	Dimensions (mm)	
A	10.0±0.3	
A1	8.0±0.2	
A2	0.94±0.1	
A3	8.7±0.1	
В	15.6±0.4	
B1	13.2±0.2	
С	4.5±0.2	
C1	1.3±0.2	
D	0.8±0.2	
D1	0.5±0.1	
Е	10.0±0.3	
F	2.8±0.1	
Н	3.6±0.1	
K	3.1±0.2	
L	1.3±0.4	
M	1.38±0.1	
M1	1.28±0.1	
N	2.54 (typ)	
P	2.4±0.3	
Q	9.15±0.25	

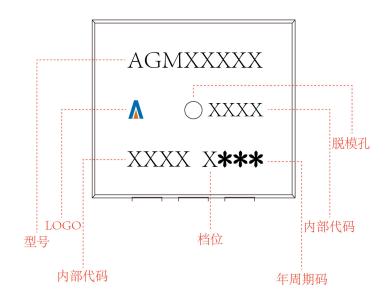


TO-220 Marking Instructions:

Model1:



Model2:





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